Document Title

32Kx8 Bit High Speed Static RAM(5V Operating), Evolutionary Pin out.
Operated at Commercial Temperature Range.

Revision History

Rev No.	History	Draft Data	Remark
Rev. 0.0	Initial release with Preliminary.	Apr. 1st, 1994	Preliminary
Rev. 1.0	Release to final Data Sheet. 1. Delete Preliminary	May 14th,1994	Final
Rev. 2.0	Update A.C parameters 2.1. Updated A.C parameters	Oct. 4th, 1994	Final

Items	Previous spec. (12/15/20ns part)	Updated spec. (12/15/20ns part)
t_{OE}	- / 8/10ns	- / 7 /9 ns
t_{CW}	- /12/ - ns	- /11/ - ns
t_{HZ}	8/10/10ns	6/7/8ns
t_{OHZ}	- / 8 / - ns	- / 7 / - ns
t_{DW}	- / 9 / - ns	- / 8 / - ns

2.2. Add V_{oh1}=3.95V with the test condition as Vcc=5V±5% at 25°C

Rev. 3.0	3.1. Add 28-TSOP1 Package. 3.2. Add L-version. 3.3. Add Data Rentention Characteristics.	Feb. 22th, 1996	Final

32K x 8 Bit High-Speed CMOS Static RAM

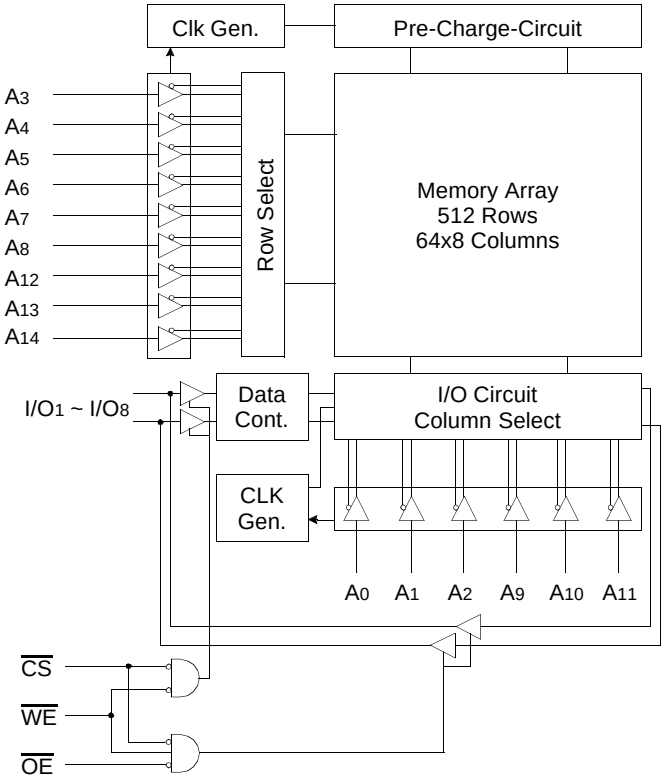
FEATURES

- Fast Access Time 12, 15, 20§À(Max.)
- Low Power Dissipation
  - Standby (TTL) : 40§Ì(Max.)
  - (CMOS) : 2§Ì(Max.)
  - 0.1§Ì(Max.)- L-ver. only
  - Operating KM68257C/CL - 12 : 165§Ì(Max.)
  - KM68257C/CL - 15 : 150§Ì(Max.)
  - KM68257C/CL - 20 : 140§Ì(Max.)
- Single 5.0V±10% Power Supply
- TTL Compatible Inputs and Outputs
- I/O Compatible with 3.3V Device
- Fully Static Operation
  - No Clock or Refresh required
- Three State Outputs
- Low Data Retention Voltage : 2V(Min.)- L-ver. only
- Standard Pin Configuration
  - KM68257C/CLP : 28-DIP-300
  - KM68257C/CLJ : 28-SOJ-300
  - KM68257C/CLTG : 28-TSOP1-0813, 4F

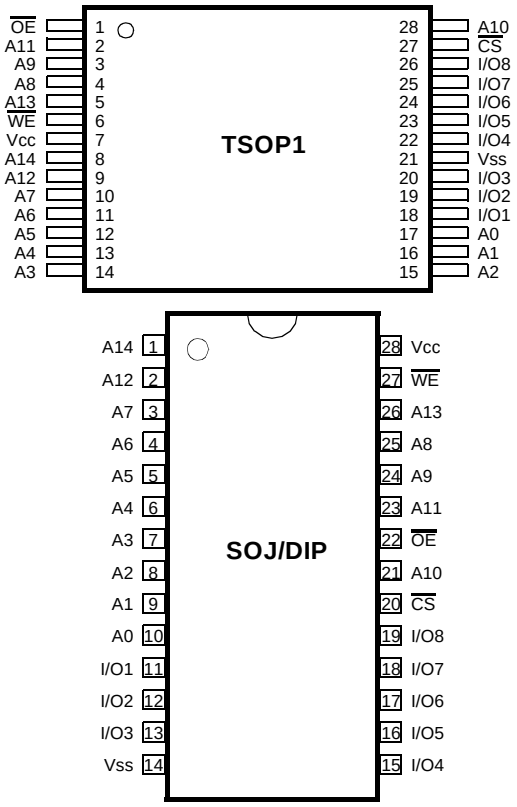
GENERAL DESCRIPTION

The KM68257C is a 262,144-bit high-speed Static Random Access Memory organized as 32,768 words by 8 bits. The KM68257C uses 8 common input and output lines and has an output enable pin which operates faster than address access time at read cycle. The device is fabricated using SAMSUNG's advanced CMOS process and designed for high-speed circuit technology. It is particularly well suited for use in high-density high-speed system applications. The KM68257C is packaged in a 300 mil 28-pin plastic DIP, SOJ or TSOP1 forward.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION*(Top View)*



PIN FUNCTION

Pin Name	Pin Function
A_0 - A_{14}	Address Inputs
$\overline{WE}$	Write Enable
$\overline{CS}$	Chip Select
$\overline{OE}$	Output Enable
I/O_1 ~ I/O_8	Data Inputs/Outputs
V_{CC}	Power(+5.0V)
V_{SS}	Ground

ABSOLUTE MAXIMUM RATINGS*

Parameter	Symbol	Rating	Unit
Voltage on Any Pin Relative to V_{SS}	V_{IN}, V_{OUT}	-0.5 to 7.0	V
Voltage on V_{CC} Supply Relative to V_{SS}	V_{CC}	-0.5 to 7.0	V
Power Dissipation	P_D	1.0	W
Storage Temperature	T_{STG}	-65 to 150	°C
Operating Temperature	T_A	0 to 70	°C

***** Stresses greater than those listed under "Absolute Maximum Rating" may cause permanent damage to the device. This is a stress ra ting only and functional operation of the device at these at these or any other conditions above those indicated in the operating sections of thi s specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS(T_A=0 to 70°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
Ground	V_{SS}	0	0	0	V
Input Low Voltage	V_{IH}	2.2	-	V_{CC}+0.5**	V
Input Low Voltage	V_{IL}	-0.5*	-	0.8	V

* V_{IL}(Min) = -2.0(Pulse Width≤10ns) for I≤20§Ì

****** V_{IH}(Max) = V_{CC}+2.0V(Pulse Width≤10ns) for I≤20§Ì

DC AND OPERATING CHARACTERISTICS(T_A=0 to 70°C,V_{CC}=5.0V±10% unless otherwise specified)

Parameter	Symbol	Test Conditions		Min	Max	Unit
Input Leakage Current	I_{LI}	V_{IN} = V_{SS} to V_{CC}		-2	2	µA
Output Leakage Current	I_{LO}	$\overline{CS}$=V_{IH} or $\overline{OE}$=V_{IH} or $\overline{WE}$=V_{IL} V_{OUT} = V_{SS} to V_{CC}		-2	2	µA
Operating Current	I_{CC}	Min. Cycle, 100% Duty $\overline{CS}$=V_{IL}, V_{IN} = V_{IH} or V_{IL}, I_{OUT}=0mA	12ns	-	165	§Ì
			15ns	-	150	
			20ns	-	140	
Standby Current	I_{SB}	Min. Cycle, $\overline{CS}$=V_{IH}		-	40	§Ì
	I_{SB1}	f=0MHz, $\overline{CS}$≥V_{CC}-0.2V, V_{IN}≥V_{CC}-0.2V or V_{IN}≤0.2V	Normal	-	2	§Ì
			L-ver	-	0.1	
Output Low Voltage Level	V_{OL}	I_{OL}=8mA		-	0.4	V
Output High Voltage Level	V_{OH}	I_{OH}=-4mA		2.4	-	V
	V_{OH1}*	I_{OH1}=0.1mA		-	3.95	V

* V_{CC}=5.0V±5% Temp.=25°C

CAPACITANCE*(T_A =25°C, f=1.0MHz)

Item	Symbol	Test Conditions	MIN	Max	Unit
Input/Output Capacitance	$C_{I/O}$	$V_{I/O}$=0V	-	8	pF
Input Capacitance	C_{IN}	V_{IN}=0V	-	7	pF

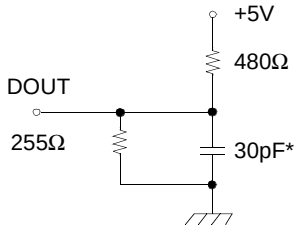
* NOTE : Capacitance is sampled and not 100% tested.

AC CHARACTERISTICS(T_A=0 to 70°C, V_{CC}=5.0V±10%, unless otherwise noted.)

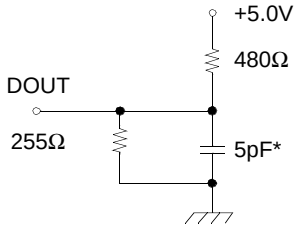
TEST CONDITIONS

Parameter	Value
Input Pulse Levels	0V to 3V
Input Rise and Fall Times	3§À
Input and Output timing Reference Levels	1.5V
Output Loads	See below

Output Loads(A)



Output Loads(B)
for t_{HZ}, t_{LZ}, t_{WHZ}, t_{OW}, t_{OLZ} & t_{OHZ}



* Including Scope and Jig Capacitance

READ CYCLE

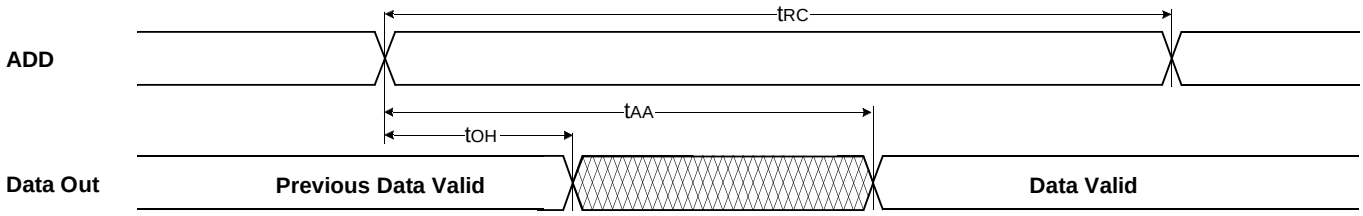
Parameter	Symbol	KM68257C/CL-12		KM68257C/CL-15		KM68257C/CL-20		Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t_{RC}	12	-	15	-	20	-	§À
Address Access Time	t_{AA}	-	12	-	15	-	20	§À
Chip Select to Output	t_{CO}	-	12	-	15	-	20	§À
Output Enable to Valid Output	t_{OE}	-	6	-	7	-	9	§À
Chip Enable to Low-Z Output Access	t_{LZ}	3	-	3	-	3	-	§À
Output Enable to Low-Z Output	t_{OLZ}	0	-	0	-	0	-	§À
Chip Disable to High-Z Output	t_{HZ}	0	6	0	7	0	10	§À
Output Disable to High-Z Output	t_{OHZ}	0	6	0	7	0	10	§À
Output Hold from Address Change	t_{OH}	3	-	3	-	3	-	§À
Chip Selection to Power Up Time	t_{PU}	0	-	0	-	0	-	§À
Chip Selection to Power DownTime	t_{PD}	-	12	-	15	-	20	§À

WRITE CYCLE

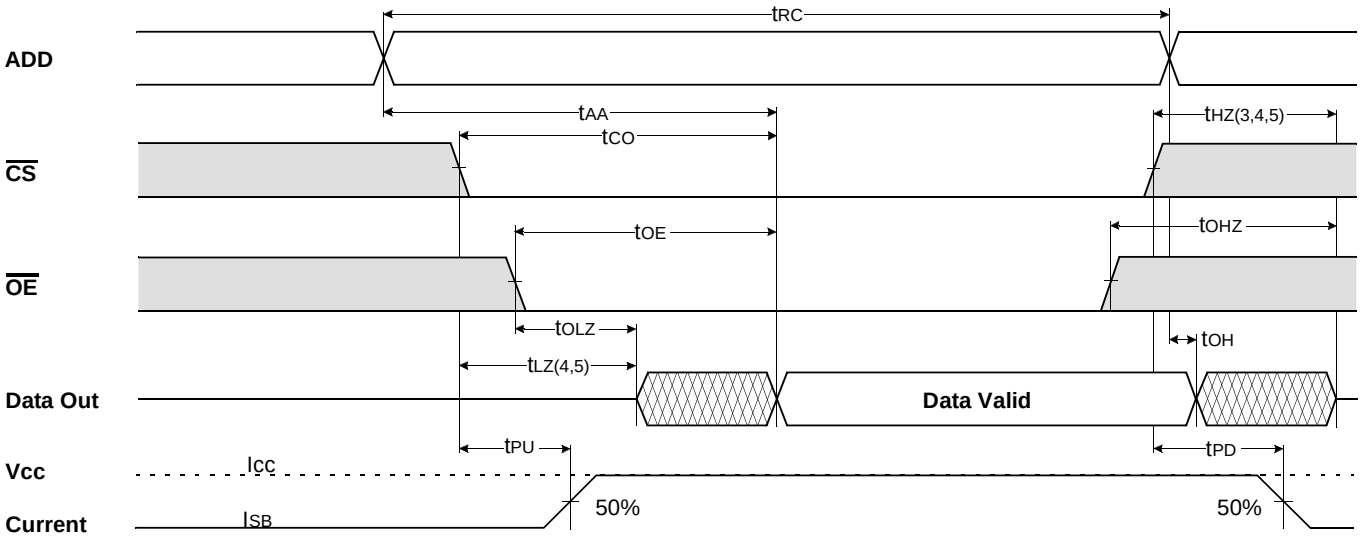
Parameter	Symbol	KM68257C/CL-12		KM68257C/CL-15		KM68257C/CL-20		Unit
		Min	Max	Min	Max	Min	Max	
Write Cycle Time	tWC	12	-	15	-	20	-	§À
Chip Select to End of Write	tCW	9	-	11	-	13	-	§À
Address Setup Time	tAS	0	-	0	-	0	-	§À
Address Valid to End of Write	tAW	9	-	12	-	13	-	§À
Write Pulse Width($\overline{OE}$ High)	tWP	9	-	12	-	13	-	§À
Write Pulse Width($\overline{OE}$ Low)	tWP1	12	-	15	-	20	-	§À
Write Recovery Time	tWR	0	-	0	-	0	-	§À
Write to Output High-Z	tWHZ	0	6	0	8	0	8	§À
Data to Write Time Overlap	tDW	7	-	8	-	10	-	§À
Data Hold from Write Time	tDH	0	-	0	-	0	-	§À
End Write to Output Low-Z	tOW	0	-	0	-	0	-	§À

TIMING DIAGRAMS

TIMING WAVE FORM OF READ CYCLE(1)(Address Controlled, $\overline{CS}$=$\overline{OE}$=VIL, $\overline{WE}$=VIH)



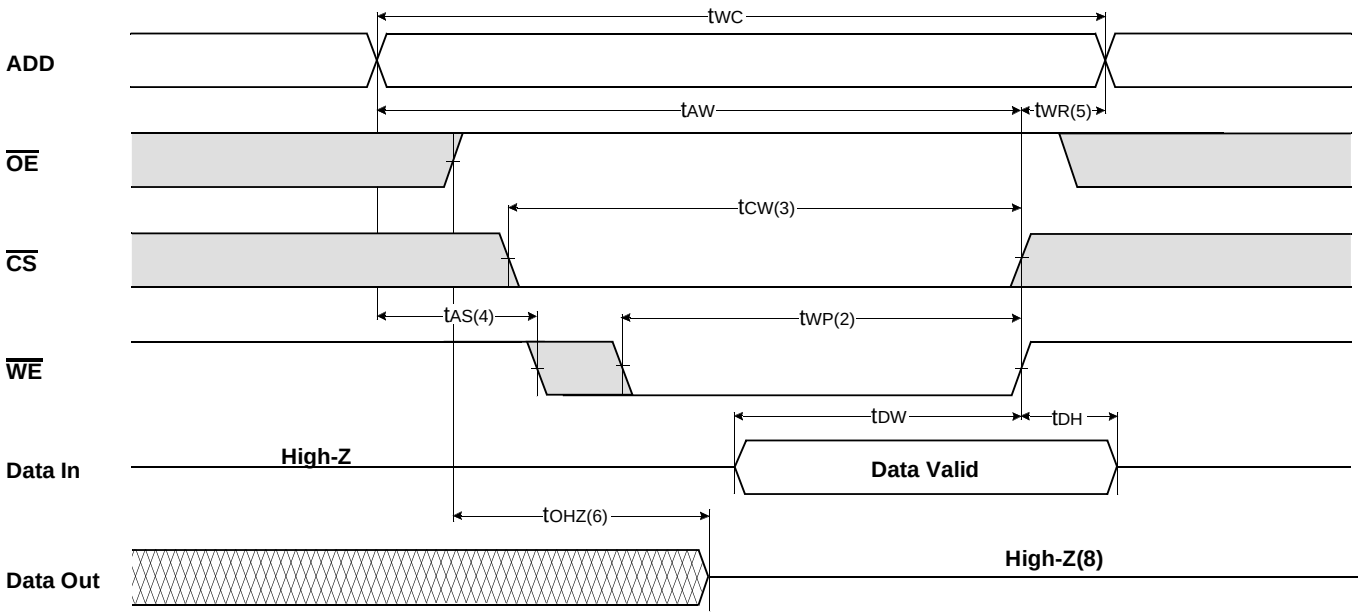
TIMING WAVE FORM OF READ CYCLE(2)($\overline{WE}$=VIH)



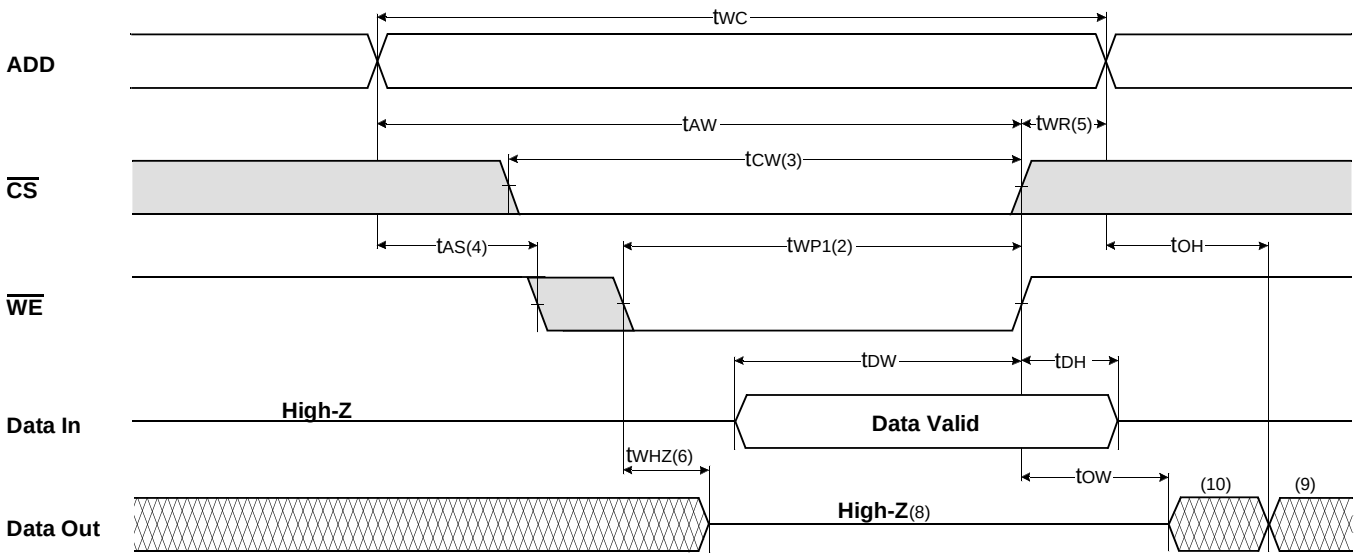
NOTES(READ CYCLE)

1. $\overline{WE}$ is high for read cycle.
2. All read cycle timing is referenced from the last valid address to the first transition address.
3. tHZ and tOHZ are defined as the time at which the outputs achieve the open circuit condition and are not referenced to VOH or VOL Levels.
4. At any given temperature and voltage condition, tHZ(Max.) is less than tLZ (Min.) both for a given device and from device to device.
5. Transition is measured ±200§Æ from steady state voltage with Load(B). This parameter is sampled and not 100% tested.
6. Device is continuously selected with $\overline{CS}$=VIL.
7. Address valid prior to coincident with $\overline{CS}$ transition low.
8. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycl e.

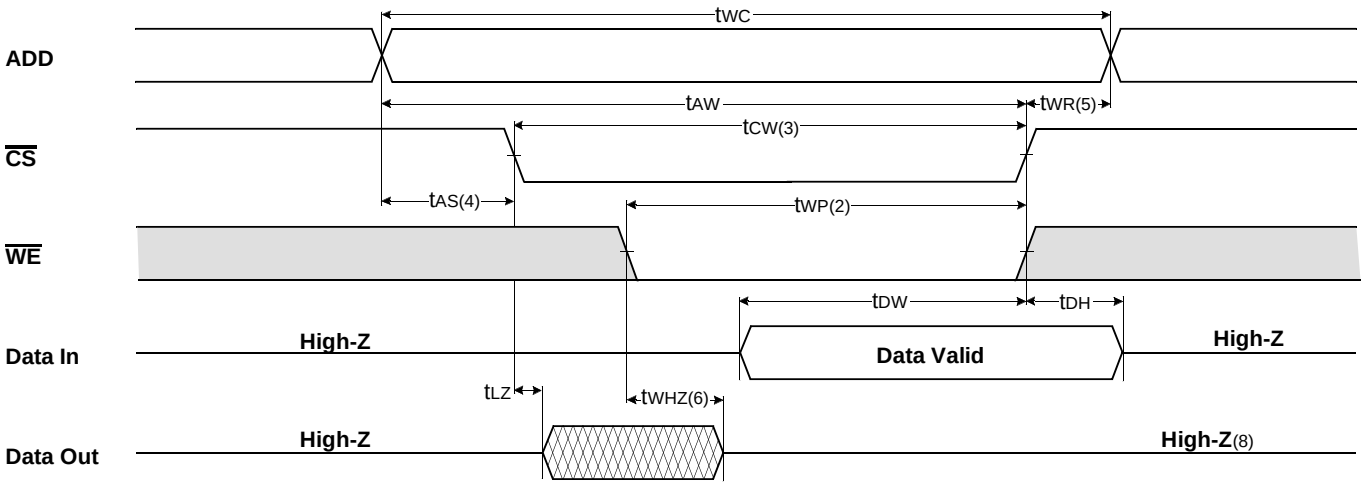
TIMING WAVE FORM OF WRITE CYCLE(1)($\overline{OE}$=Clock)



TIMING WAVE FORM OF WRITE CYCLE(2) ($\overline{OE}$=Low Fixed)



TIMING WAVE FORM OF WRITE CYCLE(3) ($\overline{CS}$=Controlled)



NOTES(WRITE CYCLE)

1. All write cycle timing is referenced from the last valid address to the first transition address.
2. A write occurs during the overlap of a low $\overline{CS}$ and $\overline{WE}$. A write begins at the latest transition $\overline{CS}$ going low and $\overline{WE}$ going low ; A write ends at the earliest transition $\overline{CS}$ going high or $\overline{WE}$ going high. t_{WP} is measured from the beginning of write to the end of write.
3. t_{CW} is measured from the later of $\overline{CS}$ going low to end of write.
4. t_{AS} is measured from the address valid to the beginning of write.
5. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as $\overline{CS}$ or $\overline{WE}$ going high.
6. If $\overline{OE}$, $\overline{CS}$ and $\overline{WE}$ are in the Read Mode during this period, the I/O pins are in the output low-Z state. Inputs of opposite phase of the output must not be applied because bus contention can occur.
7. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.
8. If $\overline{CS}$ goes low simultaneously with $\overline{WE}$ going or after $\overline{WE}$ going low, the outputs remain high impedance state.
9. Dout is the read data of the new address.
10. When $\overline{CS}$ is low : I/O pins are in the output state. The input signals in the opposite phase leading to the output should not be applied.

FUNCTIONAL DESCRIPTION

$\overline{CS}$	$\overline{WE}$	$\overline{OE}$	Mode	I/O Pin	Supply Current
H	X	X*	Not Select	High-Z	I_{SB}, I_{SB1}
L	H	H	Output Disable	High-Z	I_{CC}
L	H	L	Read	D_{OUT}	I_{CC}
L	L	X	Write	D_{IN}	I_{CC}

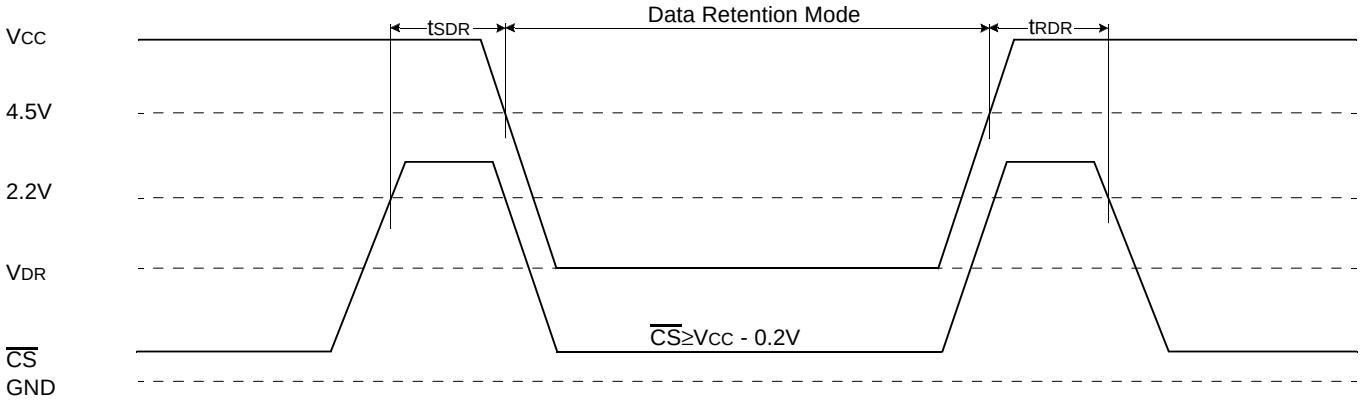
* NOTE : X means Don't Care.

DATA RETENTION CHARACTERISTICS*(T_A = 0 to 70°C)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
V_{CC} for Data Retention	V_{DR}	$\overline{CS} \geq V_{CC}$ - 0.2V	2.0	-	5.5	V
Data Retention Current	I_{DR}	V_{CC} = 3.0V, $\overline{CS} \geq V_{CC}$ - 0.2V $V_{IN} \geq V_{CC}$ - 0.2V or $V_{IN} \leq 0.2V$	-	-	0.07	§Ì
Data Retention Set-Up Time	t_{SDR}	See Data Retention Wave form(below)	0	-	-	ns
Recovery Time	t_{RDR}		5	-	-	ms

* L-Ver only.

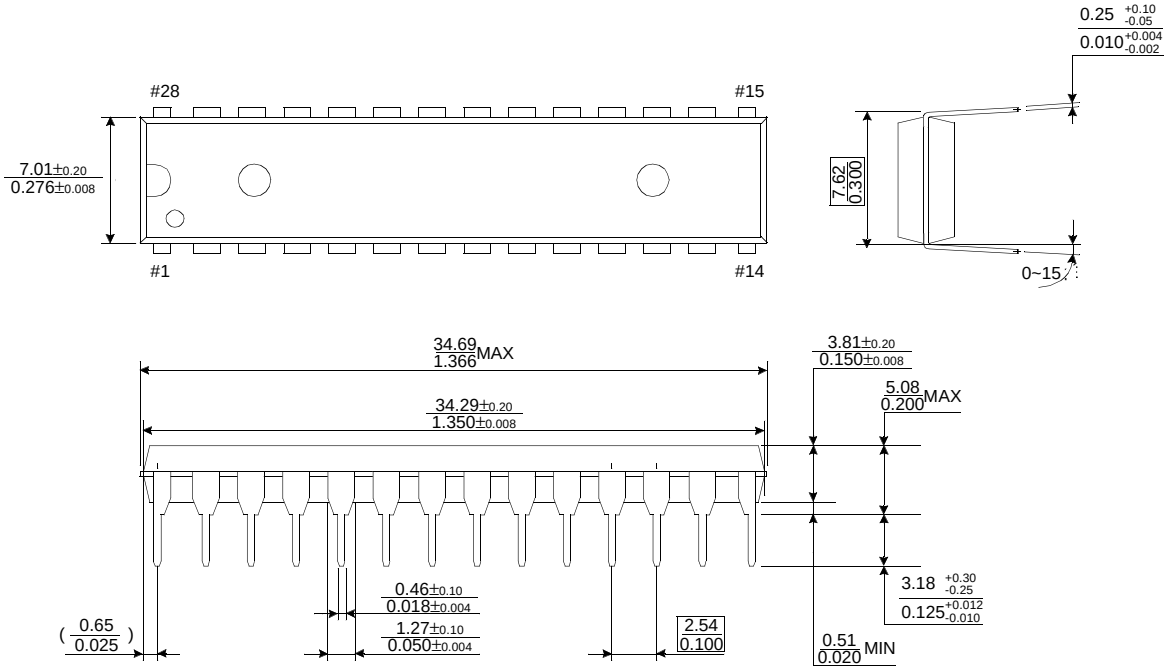
DATA RETENTION WAVE FORM($\overline{CS}$ Controlled)



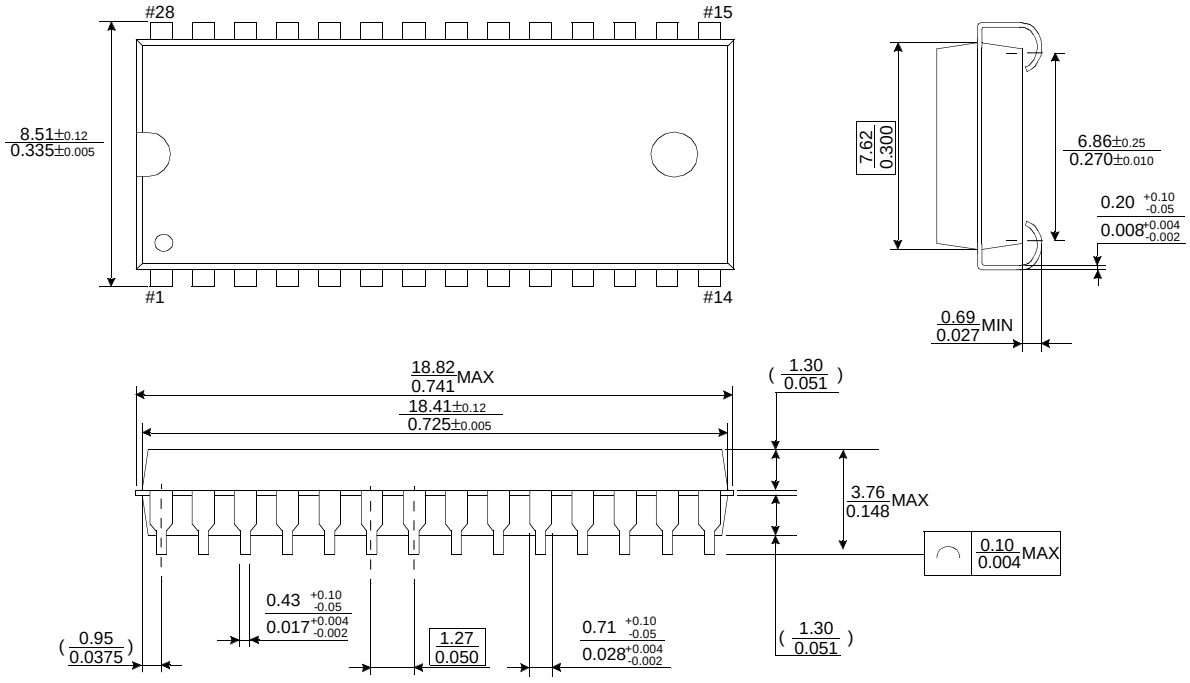
PACKAGE DIMENSIONS

28-DIP-300

Units : Inches (millimeters)



28-SOJ-300



PACKAGE DIMENSIONS

28-TSOP1-0813.4F

Units : Inches (millimeters)